

## N-Channel Power MOSFET

### Description

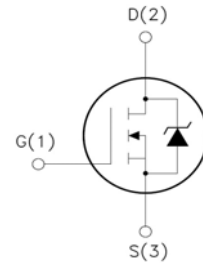
The DMN10H220LE-13 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. It is ESD protected.

### General Features

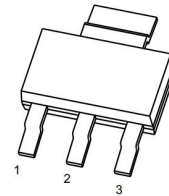
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

### Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply
- Motor control



Schematic diagram



SOT-223

### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter                                        | Symbol         | Limit      | Unit             |
|--------------------------------------------------|----------------|------------|------------------|
| Drain-Source Voltage                             | $V_{DS}$       | 100        | V                |
| Gate-Source Voltage                              | $V_{GS}$       | $\pm 20$   | V                |
| Drain Current-Continuous                         | $I_D$          | 5          | A                |
| Drain Current-Pulsed <sup>(Note 1)</sup>         | $I_{DM}$       | 21         | A                |
| Maximum Power Dissipation                        | $P_D$          | 5          | W                |
| Operating Junction and Storage Temperature Range | $T_J, T_{STG}$ | -55 To 150 | $^\circ\text{C}$ |

### Thermal Characteristic

|                                                             |                 |      |                    |
|-------------------------------------------------------------|-----------------|------|--------------------|
| Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup> | $R_{\theta JA}$ | 41.7 | $^\circ\text{C/W}$ |
|-------------------------------------------------------------|-----------------|------|--------------------|

### Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter                       | Symbol     | Condition                 | Min | Typ | Max | Unit |
|---------------------------------|------------|---------------------------|-----|-----|-----|------|
| <b>Off Characteristics</b>      |            |                           |     |     |     |      |
| Drain-Source Breakdown Voltage  | $BV_{DSS}$ | $V_{GS}=0V, I_D=250\mu A$ | 100 | 110 | -   | V    |
| Zero Gate Voltage Drain Current | $I_{DSS}$  | $V_{DS}=80V, V_{GS}=0V$   | -   | -   | 800 | nA   |

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|                                    |                     |                                                                                                             |   |     |      |    |
|------------------------------------|---------------------|-------------------------------------------------------------------------------------------------------------|---|-----|------|----|
| Gate-Body Leakage Current          | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V                                                                  | - | -   | ±100 | nA |
| On Characteristics (Note 3)        |                     |                                                                                                             |   |     |      |    |
| Gate Threshold Voltage             | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                                    | 1 | 1.8 | 3    | V  |
| Drain-Source On-State Resistance   | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =3A                                                                    |   | 125 | 145  | mΩ |
| Forward Transconductance           | g <sub>FS</sub>     | V <sub>DS</sub> =5V, I <sub>D</sub> =2.9A                                                                   | - | 8   | -    | S  |
| Dynamic Characteristics (Note4)    |                     |                                                                                                             |   |     |      |    |
| Input Capacitance                  | C <sub>Iss</sub>    | V <sub>DS</sub> =25V, V <sub>GS</sub> =0V,<br>F=1.0MHz                                                      | - | 210 | -    | PF |
| Output Capacitance                 | C <sub>Oss</sub>    |                                                                                                             | - | 30  | -    | PF |
| Reverse Transfer Capacitance       | C <sub>rss</sub>    |                                                                                                             | - | 14  | -    | PF |
| Switching Characteristics (Note 4) |                     |                                                                                                             |   |     |      |    |
| Turn-on Delay Time                 | t <sub>d(on)</sub>  | V <sub>DD</sub> =50V, I <sub>D</sub> =5A, R <sub>L</sub> =15Ω<br>V <sub>GS</sub> =10V, R <sub>G</sub> =2.5Ω | - | 15  | -    | nS |
| Turn-on Rise Time                  | t <sub>r</sub>      |                                                                                                             | - | 3.4 | -    | nS |
| Turn-Off Delay Time                | t <sub>d(off)</sub> |                                                                                                             | - | 21  | -    | nS |
| Turn-Off Fall Time                 | t <sub>f</sub>      |                                                                                                             | - | 3.1 | -    | nS |
| Total Gate Charge                  | Q <sub>g</sub>      | V <sub>DS</sub> =50V, I <sub>D</sub> =5A,<br>V <sub>GS</sub> =10V                                           |   | 4.5 |      | nC |
| Gate-Source Charge                 | Q <sub>gs</sub>     |                                                                                                             | - | 1.5 | -    | nC |
| Gate-Drain Charge                  | Q <sub>gd</sub>     |                                                                                                             | - | 1.2 | -    | nC |
| Drain-Source Diode Characteristics |                     |                                                                                                             |   |     |      |    |
| Diode Forward Voltage (Note 3)     | V <sub>SD</sub>     | V <sub>GS</sub> =0V, I <sub>S</sub> =6A                                                                     | - | -   | 1.2  | V  |
| Diode Forward Current (Note 2)     | I <sub>S</sub>      |                                                                                                             | - | -   | 5    | A  |

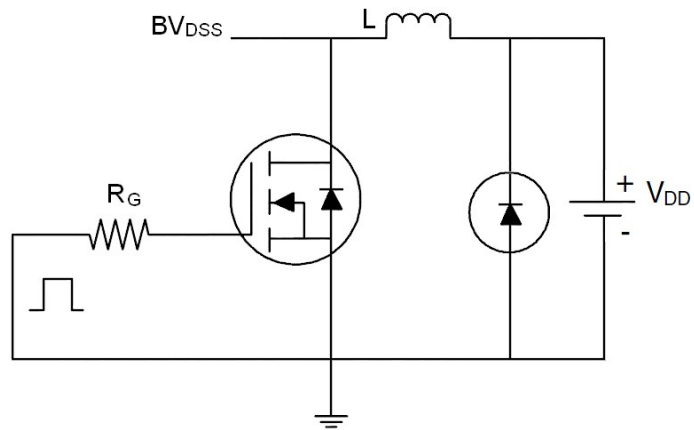
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

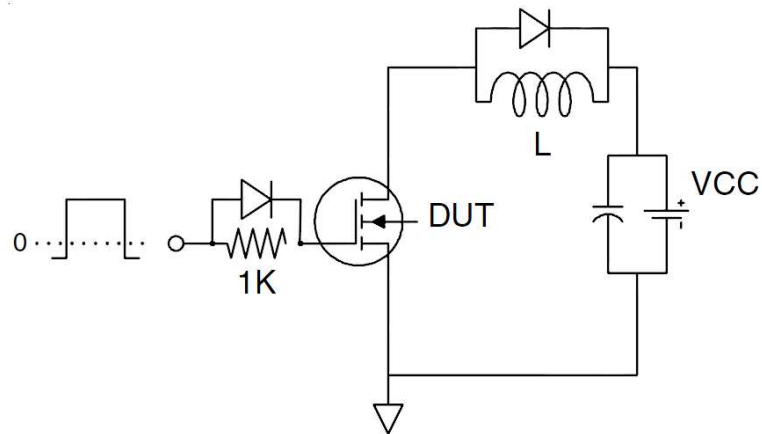
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**Test Circuit**

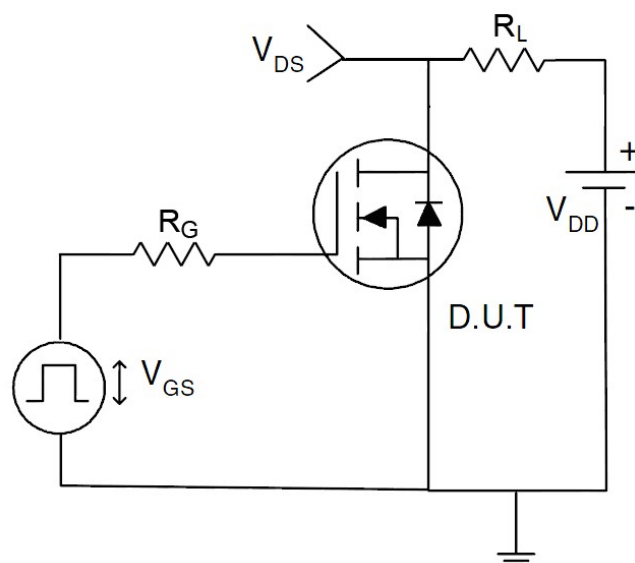
**1)  $E_{AS}$  test circuit**



**2) Gate charge test circuit**



**3) Switch Time Test Circuit**



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Typical Electrical and Thermal Characteristics (curves)

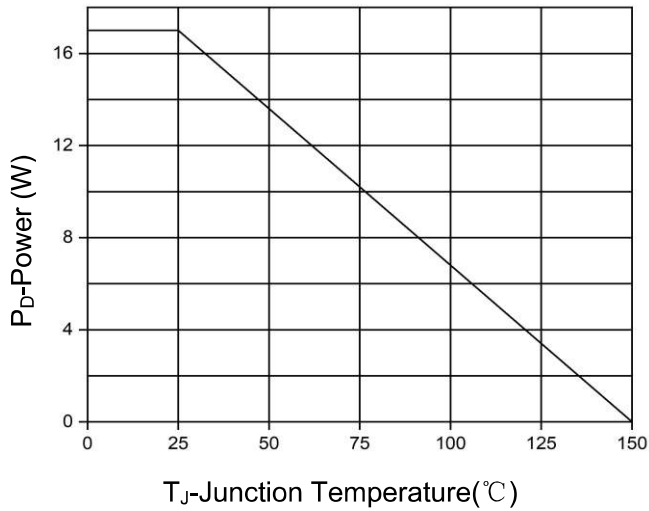


Figure 1. Power Dissipation

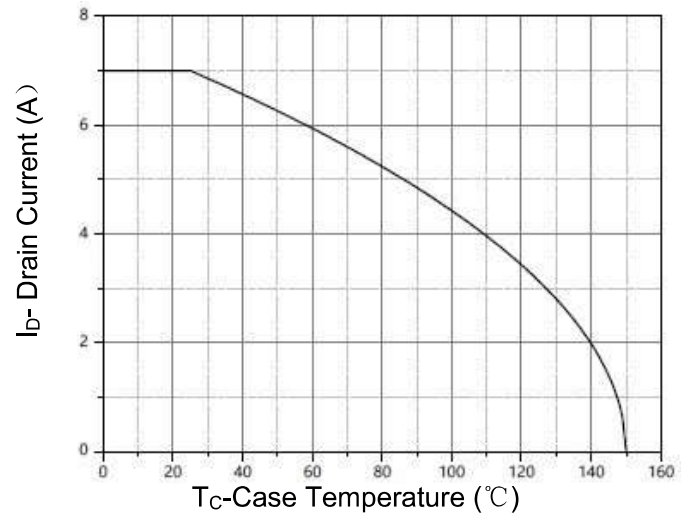


Figure 2. Drain Current

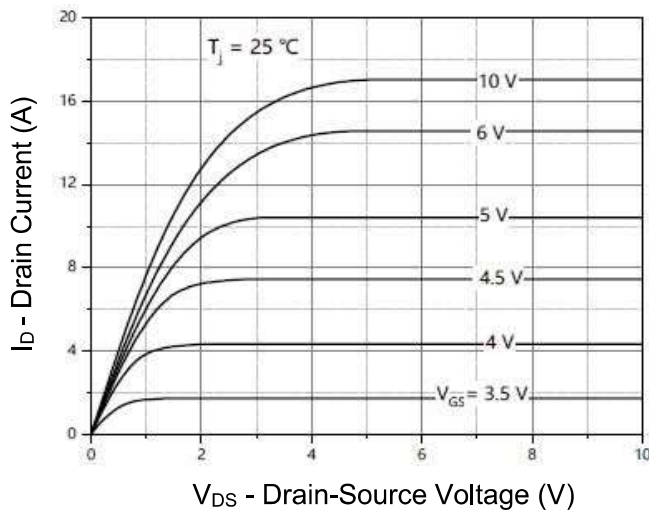


Figure 3. Output characteristics

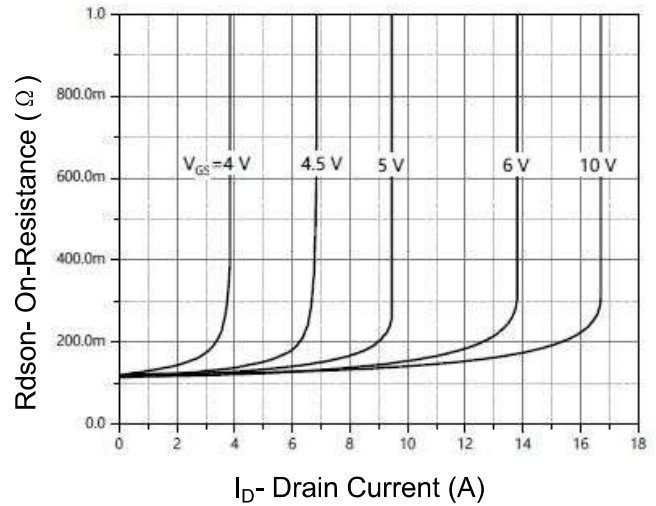


Figure 4. Drain-Source On-state resistance

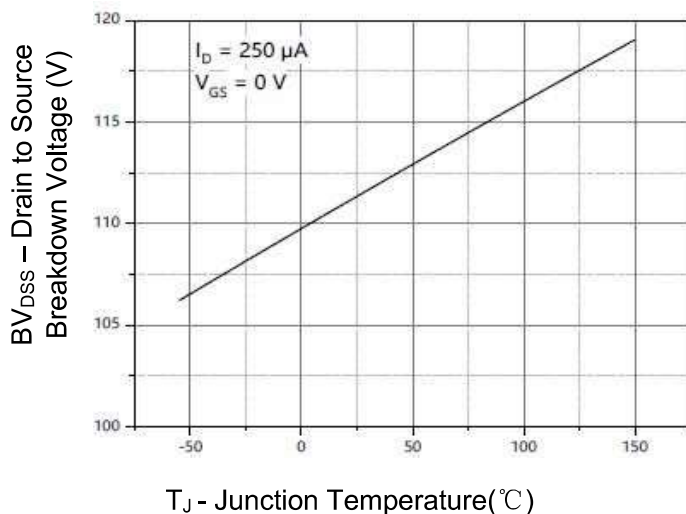


Figure 5. Drain-source breakdown voltage

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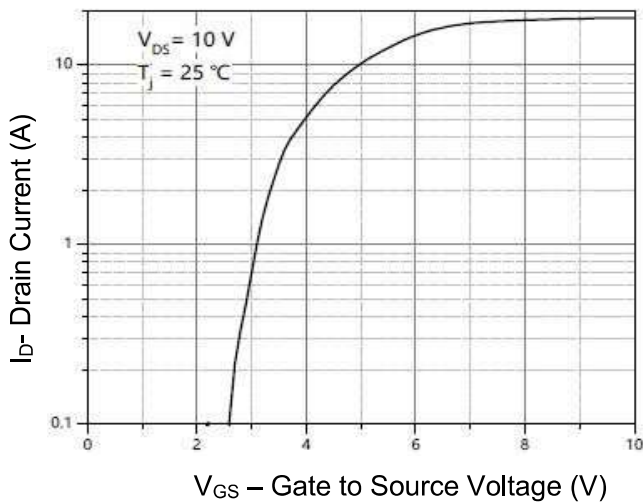


Figure 6. Transfer Characteristics

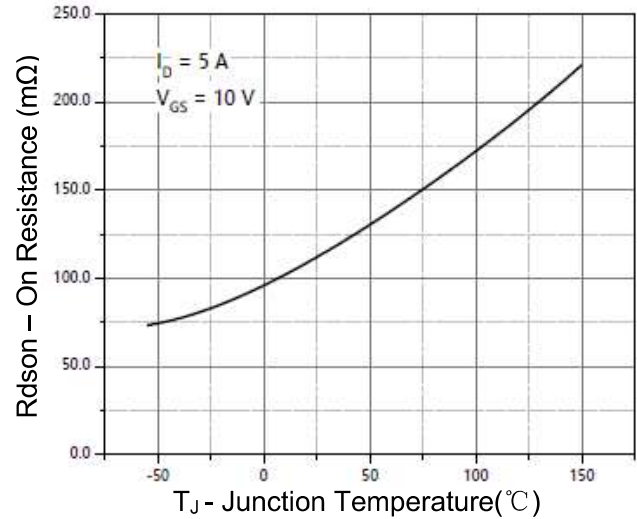


Figure 7. Drain-Source On-State Resistance

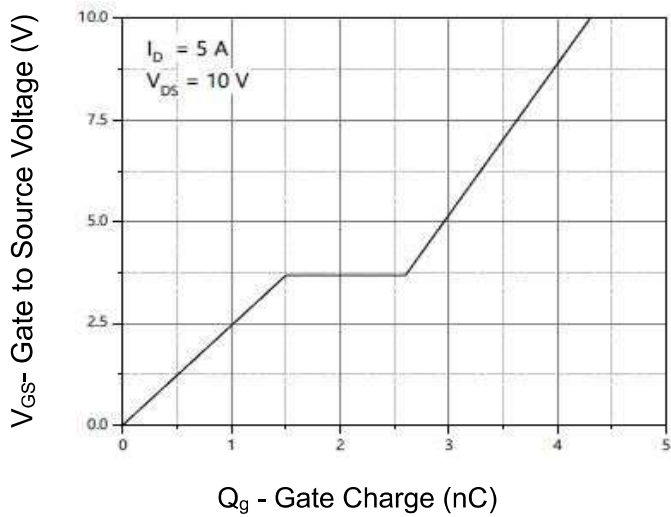


Figure 8. Gate Charge

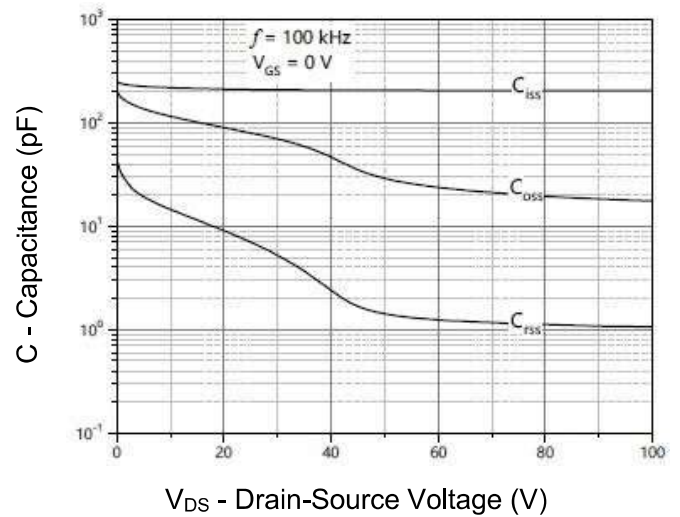


Figure 9 . Capacitance vs Vds

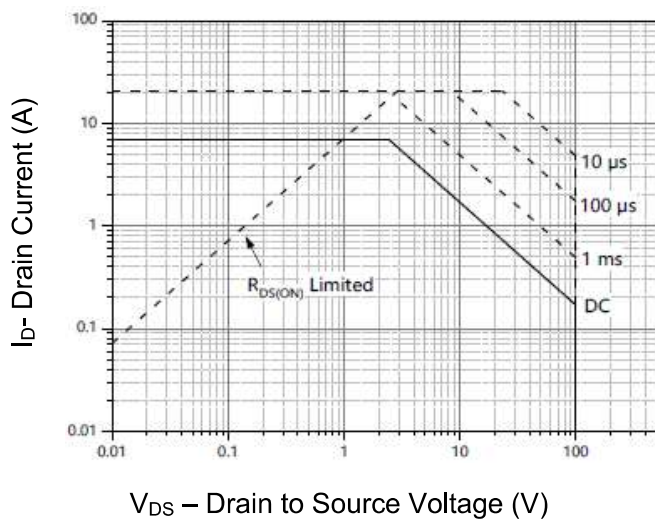


Figure 10. Safe Operation Area

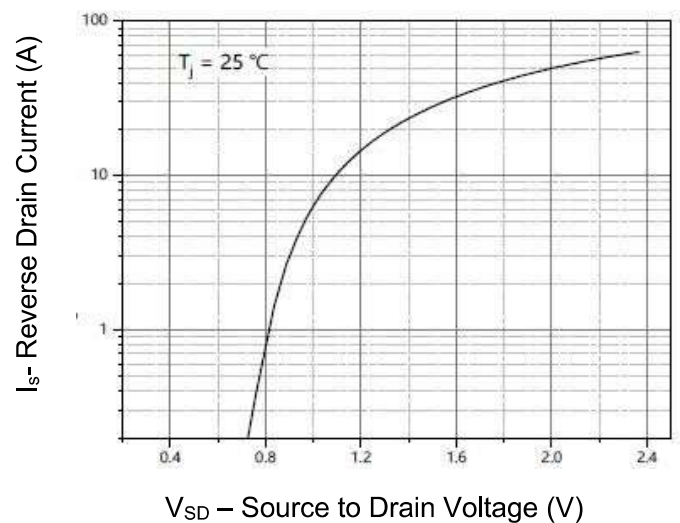


Figure 11. Source- Drain Diode Forward